

# HIGH VOLUME METALIZING REDUCE RISK INVEST WISELY IMPROVE PROFITS

**J. Lynema**



**A. Plaisted**



**G. Vergason**



Vergason Technology, Inc.

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# *High Volume Metalizing*

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- **Production Pressures**
- **Processing Definitions**
- **Production Requirements**
- **Profit Leaks**
- **Summary**

# *Production Pressures*

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- **Improve throughput and quality**
- **Reduce costs**
- **Coated substrates being integrated in larger and higher value-add assemblies**
- **Issues not market unique**
- **Coordinating improvements and efforts**
  - Industrial user
  - Equipment supplier
  - Consumable supplier
- **Global competition in a “flat world”**
- **Increased recycling focus**

# *Processing Definitions*

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## **Large Batch Systems: non-synchronous**

- **Aluminum coating – thermal based**
- **Polymer top coating – DC, AC, some RF**
- **Large floor space requirements**
  - Large chamber ~2 meter diameter
  - Fixturing storage and stripping
- **Reduced quality yields ~90%**
- **Usually in expensive clean-room**
- **Substrates boxed and transported**
- **Multiple operators**
- **20 to 40 minute cycle times – process dependent**

# *Processing Definitions*

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## **Rapid Cycle Systems: synchronous production**

- **High & low melting point metals – sputter/cat arc**
- **Polymer base & top coatings – AC, some RF**
- **Reduced footprint**
  - Chambers to match molding machine output <1 meter diameter
  - Smaller and fewer fixtures
- **Increased quality yields - >99%**
- **No clean-room required**
- **Substrates coated directly after molding**
  - Clean, warm, dry
- **Single operator**
- **0.5 to 6 minute cycle times – process dependent**

# *Production Requirements*

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## **Define the coatings & deposition techniques**

- **Metals**

- Low melting point only – thermal
- High melting point only – sputtering or cat arc
- All temperature ranges – sputtering
- Metal and/or reactive coatings – DC or AC power

- **Base and top coatings**

- Plasma polymerization – DC, AC, RF, ?
- High pressure or low pressure processing
- Plasma cleaning/etching

# *Production Requirements*

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- **Select production mode**
  - Synchronous
    - Highly automated
    - Very little substrate storage
  - Large batch
    - Highly manual
    - Much substrate storage
- **Work closely with suppliers in selection to optimize resources**
  - Personnel, equipment, consumables

# *Production Requirements*

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- **Contracts are won on a cost per part basis**
- **Floor space layouts**
  - Footprint, conveyors, work area, fixturing/consumable storage, support equipment
- **Capital investments**
  - Coating system, ancillary tools, fixtures, automation
- **Personnel**
  - Level of training required: operators to production planners



# *Production Requirements*

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- **Production costs**
- **Overhead**
- **Utilities**
  - Electric, chilled water, compressed air
- **Consumables**
  - Metal for deposition, gases, liquids, operational and maintenance materials

# *Production Requirements*

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- **Cost per cycle estimates** – rapid cycle, \$800,000 machine amortized over 5 years, aluminum with polymer base & top coating, 2.7 square meter coating zone, 57,200 cycles/yr

Machine	\$2.80
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Labor	\$1.92
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<u>Utilities and consumables</u>	<u>\$1.50</u>
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Cost per cycle (CPC)	\$6.22
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Cost per part = divide CPC by number of parts

# *Profit Leaks*

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- **Mismatch in the application of the coating system, consumables, utilities and personnel**
- **Over and under utilization wastes money and stresses the resources**
- **Can be greatly reduced with close cooperation between industrial user, equipment supplier and consumable supplier**

# *Profit Leaks*

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## **Coating system profit leaks**

- **Incorrectly sized chamber**
- **Wrong pumping package**
- **Venting with wet, room air**
- **Deposition power supply sizing**
  - Match with metal material and cooling
- **Poor management of cooling water**
  - Sediment, minerals, temperature, flow
- **Calibration of pressure gauges, liner cleaning**

# *Profit Leaks*

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## **Target/Cathode leaks**

- **Match thermal expansion of target and backing plate, ductile for flattening**
- **Vacuum braze improves cooling uniformity & operates at higher temperatures**
- **Screen out poor bonds by underwater ultrasonic or phased array testing**
- **Avoid thermal stress by explosive clad or other room temp processes**

# *Profit Leaks*

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## **Improper specification of target/cathode purity**

- **Adding additional 9 (99.XXX) can double or triple the material price**
- **Proving a target is 99.999% pure can be as costly as making it**
- **Reducing target poisoning elements by adding purity is expensive, better to reduce the specific contaminant at a lower cost**
- **Specifications for oxygen below 500 ppm, when acceptable deposited metal films analysis was at 25,000 ppm**

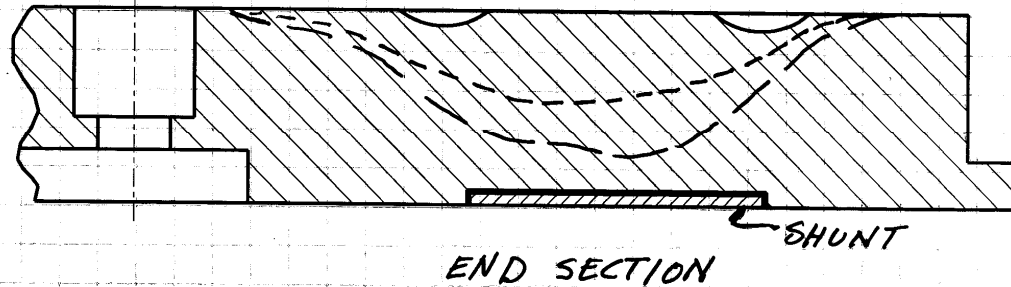
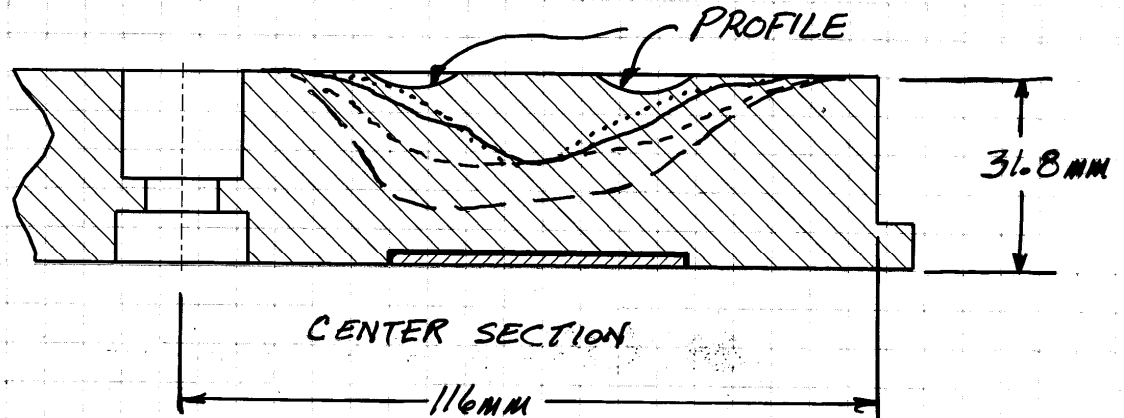
# *Profit Leaks*

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- Use ideas, such as surface profiling developed by other industries**
- **Careful placement of small secondary grooves in a target surface initiates erosion over the trench walls**
  - Result is a shallower wider trench, longer target life, and a more stable plasma over the target life
- **Compact Disc optical media uses thousands of profiled targets annually**
  - Profiles started in 1993 and are now universal
  - Benefits are life, deposition uniformity, and stability

# Reduction Of Sputter Target Trench With Profiles

TRENCH TRACINGS PROFILE/SHUNT COMBINATION



- #2 PROFILE, SHUNTED
- #2 PROFILE, UN-SHUNTED
- ..... NO PROFILE, NO SHUNT
- END OF LIFE, SHUNTED



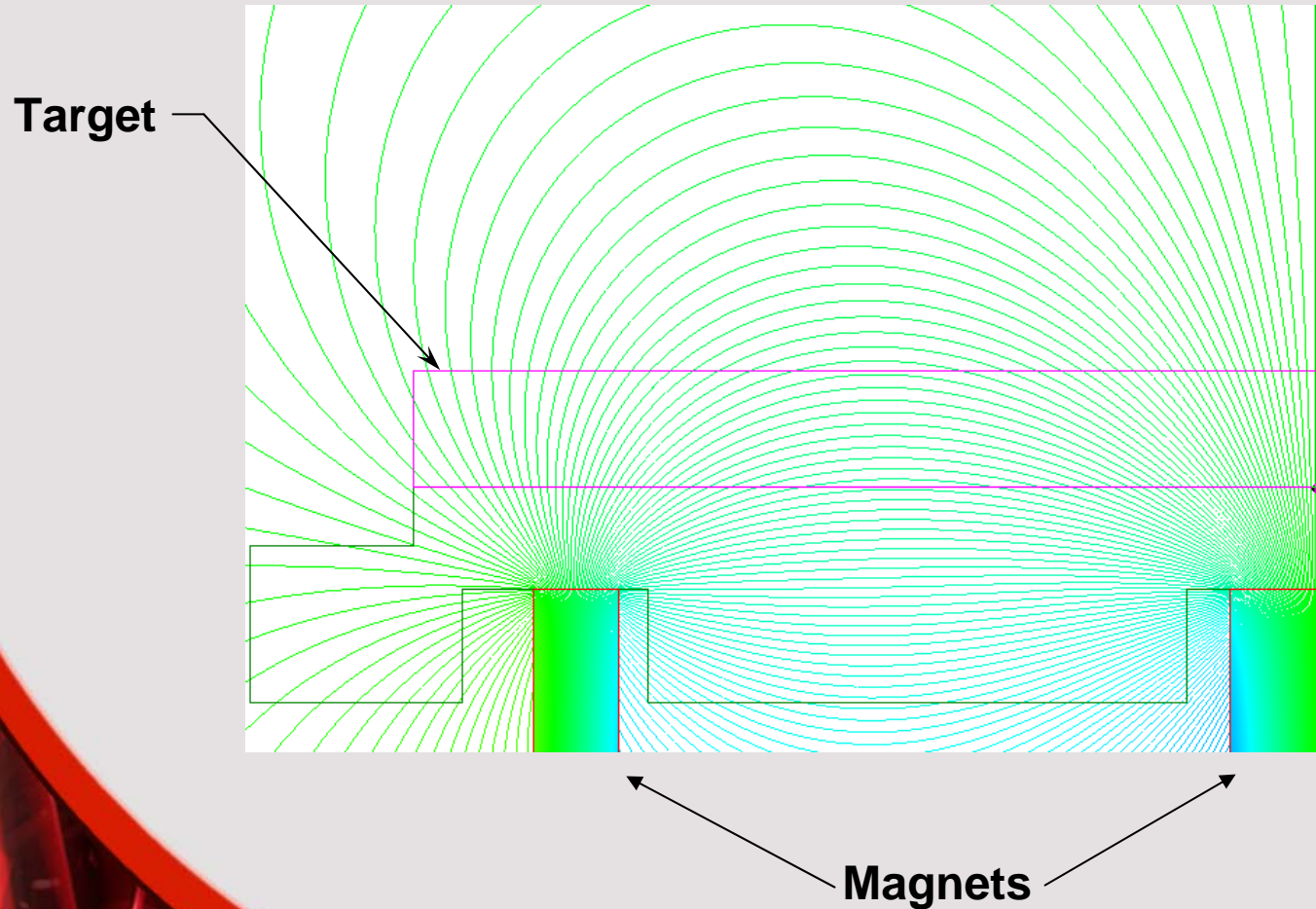
# *Profit Leaks*

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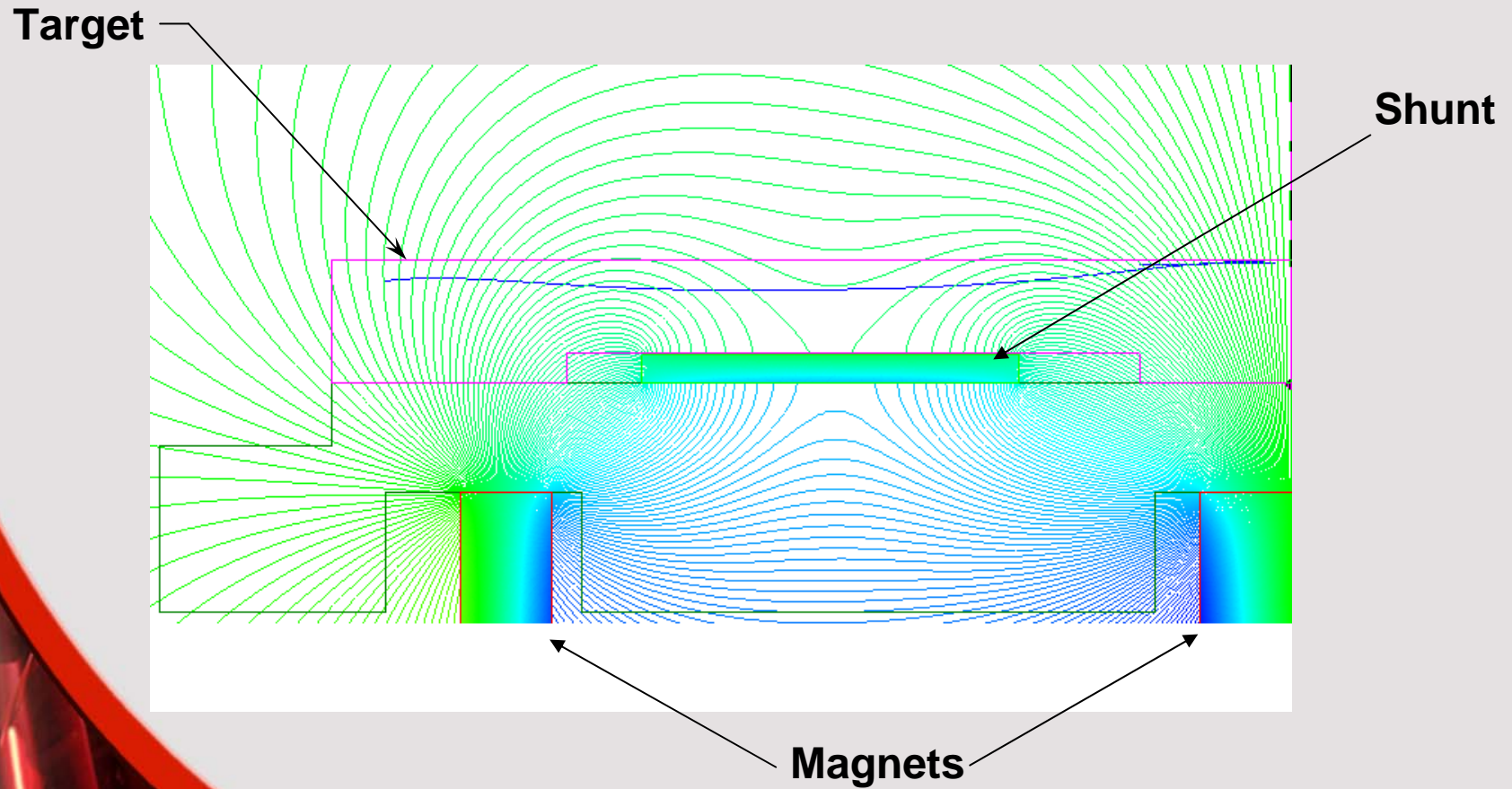
## **Underestimating benefits of magnetic shunts**

- **Profile technique starts erosion trench on a wide base**
- **As trench deepens, profiles contribute less and less**
- **A magnet shunt to enhance magnetic field shape is then introduced**
- **Technique developed by IBM in 1993 but never widely published or applied**

# *Unshunted Cathode Magnetic Field*

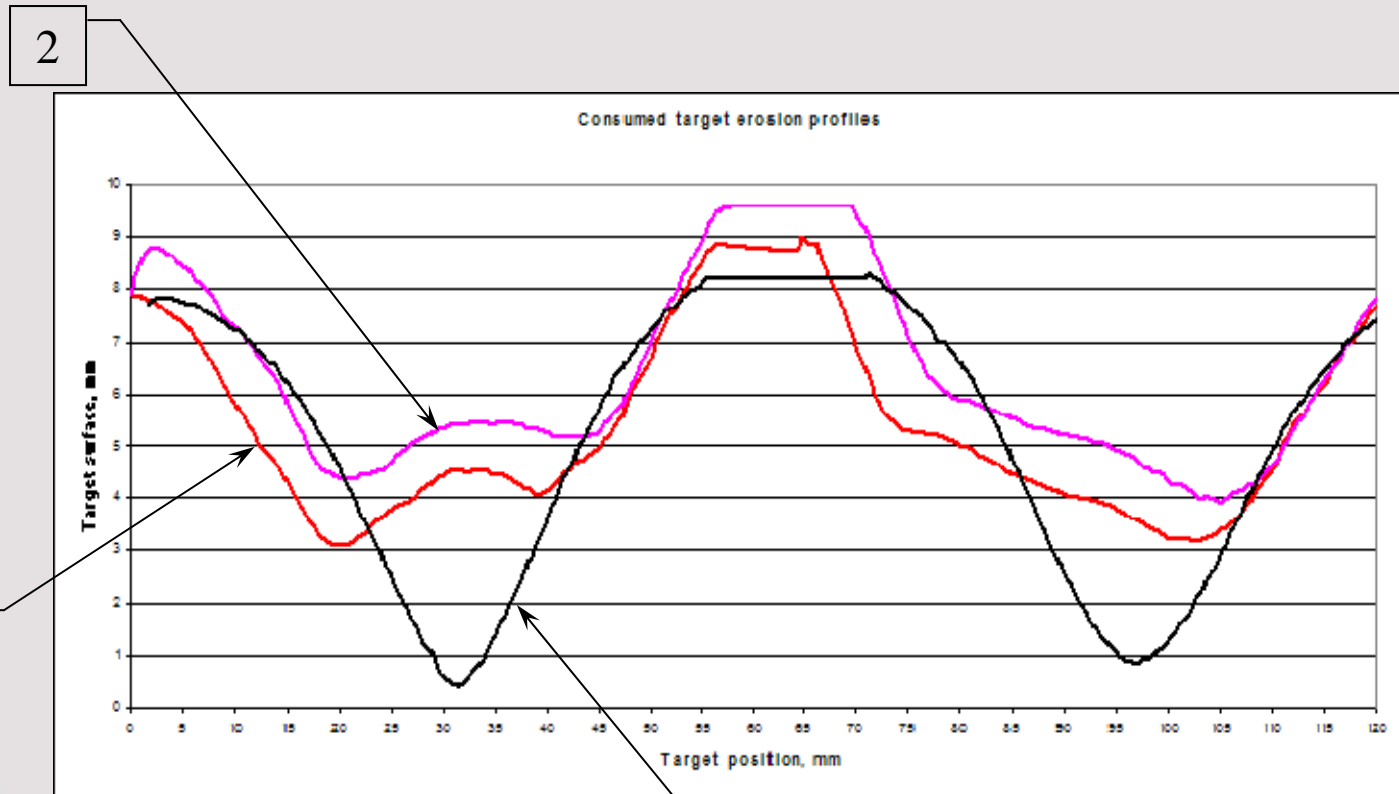


# *Shunted Cathode Magnetic Field*



# Target Erosion

## Benefits of Magnetic Shunt



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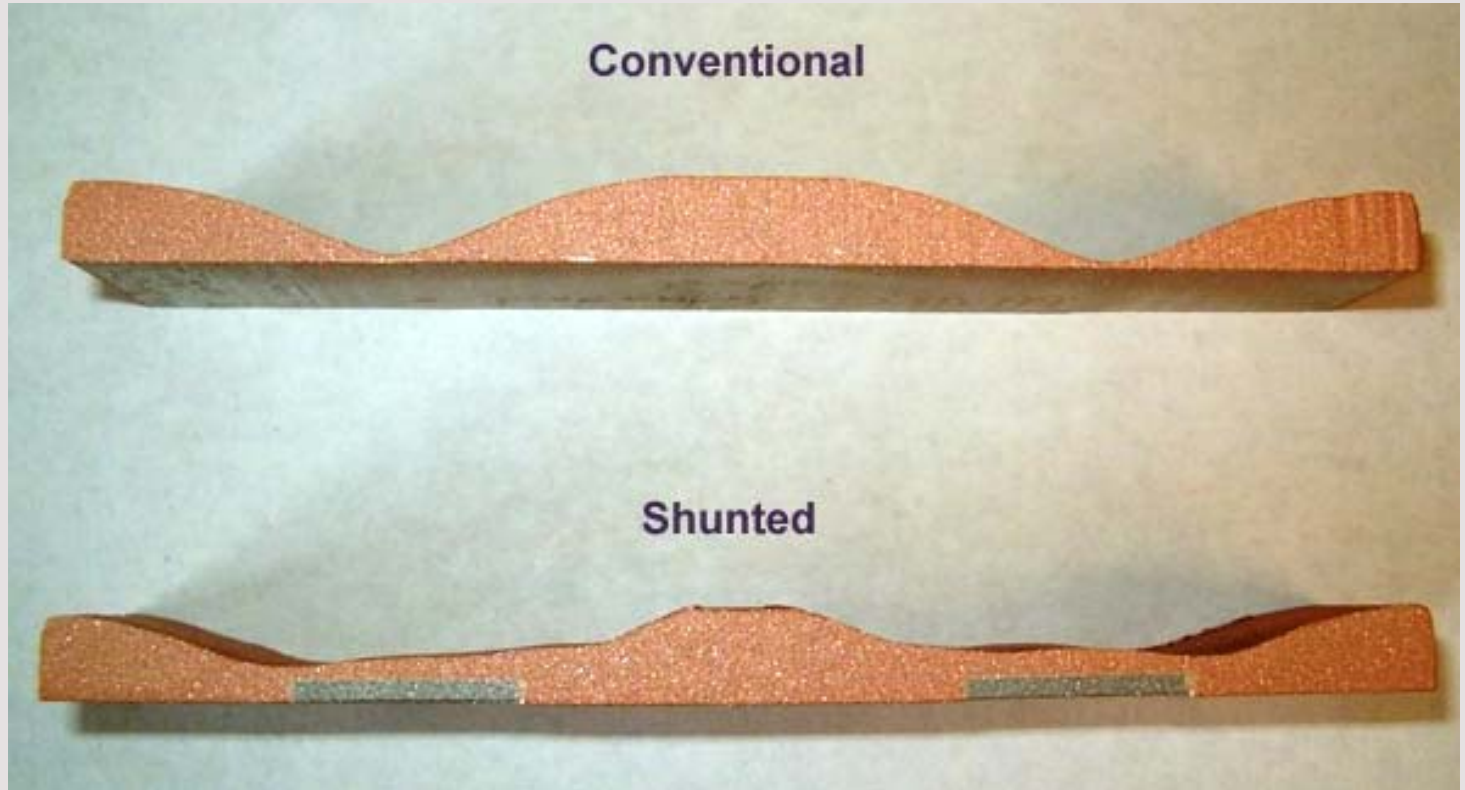
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- Target Shunt Development
1. Initial, No Shunt
  2. First Trial
  3. Second Trial

# *Shunted Target*

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# *Profit Leaks*

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## **Not considering alternative deposition techniques**

- **Rotary targets**

- Can exceed 90% utilization of sputter targets
- 10% of surface being heated and 90% being cooled
- List of available materials is larger each year
- Shortest length is about 406mm, longest 3.8 meters
- Over 1000 cathodes in operation
- Vacuum chamber must be designed around device
- 10 kW per 300mm length has been achieved

# *Conclusion*

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- **All processes can benefit from focusing on common issues that rob profits**
- **Standard operating and maintenance procedures can reduce risks**
- **Adopting profit leak reduction plans can produce savings of 50% on consumables**
- **Working together the industrial user, equipment supplier and consumable supplier can yield profit benefits for years to come**